LBI31243B



MAINTENANCE MANUAL

136-174 MHz 40-WATT WIDEBAND TRANSMIT/RECEIVE BOARD 19D901002G2, 4-6

(PHOENIX-SX)

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DESCRIPTION

The transmit/receiver board for the Phoenix-SX radio combination contains the receiver, exciter and power amplifier. The audio processor circuitry for the transmit (microphone) audio is included on the synthesizer/interconnect board. Transmit/receiver RF frequency injection (5-15 milliwatts) is provided by a common VCO on the synthesizer/interconnect board. There are no multipliers in the exciter since the RF injection frequency from the synthesizer VCO is the transmit frequency or the receiver mixer injection frequency.

The transmit/receiver board (Tx/Rx) is located on the bottom of the radio. A block diagram of the Tx/Rx board is shown in Figure 1.

CIRCUIT ANALYSIS

Exciter

The exciter consists of amplifiers Q101-Q104 and operates over the 136-174 MHz frequency range. This wide band exciter requires no tuning.

RF injection from the synthesizer/interconnect board is applied to the base of Class A Ampl Q101 through J151, a 3 dB attenuator pad, and an impedance matching network consisting of C101, C102 and L101. This network matches the base of Q101 to 50 ohms. The 3 dB attenuator pad (R101-R103) provides a constant load for the VCO output when switching to or from the transmit mode to maintain frequency stability. Continuous 8.5V is applied to Q101 through a collector feed network consisting of L102, R106, R109, and C104-C106. Base bias is set by R104 and R105. Continuous 8.5 volts is also

supplied to Q103. Metering for Q101 is provided by TP101 in the emitter circuit.

The output of Q101 is coupled to the base of Class B amplifier, AMPL 2 (Q102), through impedance matching network consisting of C108, C109 and L103. Tx switched 8.5V is provided through a collector feed network consisting of L104, R112, R113, and C110-C112. This switched voltage provides Tx/Rx isolation, preventing Rx VCO frequencies from passing through the exciter. Q202 is turned on only in the transmit mode. Decoupling for the switched 8.5V line is provided by C107, C113 and C122.

The output of Q102 is further amplified by a 2nd Class B amplifier, AMPL 3 (Q103) and applied to the base of the exciter final amplifier Q104. An impedance matching network consisting of L107. L108, C118-C121, and C126 matches the collector circuit of Q103 to the base of Q104. Q104 provides a minimum of 2 watts across the 136-174 MHz band to the PA. The output is coupled through interconnection/test jack J201. J201 can be used when troubleshooting the exciter/ PA. It allows the technician to monitor the exciter output or to inject RF frequencies into the power amplifier by removing P201 and installing a test plug into J201-1, 3 or J201-2, 4.

Power Control

The power control circuit allows output power adjustment from 20 to 40 watts and provides overvoltge protection to automatically reduce the output power when the battery voltage exceeds 13 volts. The power control circuit consists of D101, Q105, Q106 and Q204. Q204 controls the collector voltage to exciter final amplifier Q104 which provides RF drive to the power amplifier.



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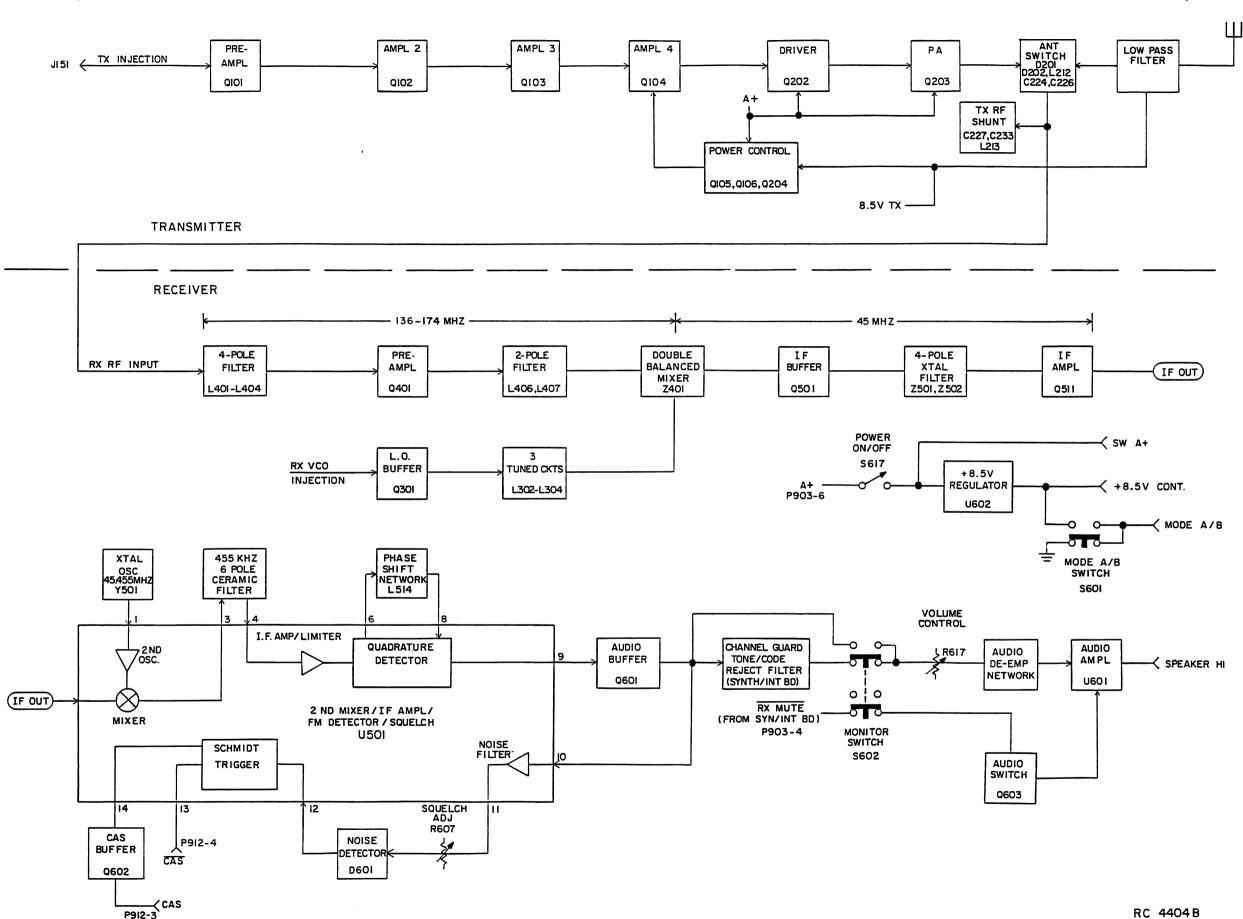


Figure 1 - Transmit/Receive Board Block Diagram

Should the battery voltage exceed 12 volts, D101 will fire and apply base voltage to Q106. (An additional 0.7 volts is required to turn Q106 on.) As Q106 turns on a parallel path is provided around R120, reducing the base voltage of Q105. Q105 decreases the base voltage applied to Q204, causing Q204 to reduce the collector voltage to exciter final amplifier Q104. Reducing the collector voltage to Q104 decreases the RF drive applied to the power amplifier, maintaining near constant RF output power.

When battery voltage is between 12 and 16 volts the RF output power will remain near rated power. Should the battery voltage exceed 16 volts output power is drastically reduced. R120 is set to provide rated output power with battery voltage at 13.6 volts DC.

POWER AMPLIFIER

The power amplifier consists of two Class C broadband, fixed tuned transistor amplifiers that amplify the two watt RF input from the exciter and provide 40 watts RF output power. No tuning is required.

The exciter output from J201 is applied to the base of driver Q202 through a 50 ohm impedance matching network consisting of C201-C203, L201, L202, and R201. The output of Q202 is taken from the collector and applied to power amplifier Q203 through an impedance matching network. This network, consisting of L205, L206, C210-C213, and R203 matches the collector impedance of Q202 to the base of PA Q203.

A+ is supplied to the driver and PA through collector feed networks consisting of C204, L203, L204 and R202 (Q202) and L207, L208, C214 and R104 (Q203). C205-C207 provide decoupling for any transient noises that may be on the line.

In the transmit mode 8.5V Tx switched voltage is applied to Tx/Rx antenna switch by Tx 8.5V switch Q604, turning pin diodes D201 and D202 on. (Q604 is controlled by DPTT.) The PA output is then coupled through impedance matching network L209, L210, C215-C219 and coupling capacitors C220 and C229 and forward bias pin diode D201 to the low pass filter and then to the antenna through J601.

L212, C224, C226, and forward biased pin diode D202 create a 1/4 wave stub across the 136-174 MHz band, presenting an open circuit to the receiver at these RF frequencies, thus directing output power through the low pass filter and out of the antenna.

In the receive mode D201 and D202 are turned off, the AC short is removed and the 1/4 wave stub now presents a 50 ohm impedance to the receiver, allowing the received RF to pass through the low pass filter to the receiver. Pin diode D201 prevents the receive signal from getting into the transmitter.

RECEIVER

The receiver is a dual conversion, superheterodyne FM receiver designed for operation in the 136-174 MHz frequency range. Regulated 8.5 volts is used to power all receiver stages except for the audio PA IC, which operates from the A+supply.

The receiver has intermediate frequencies of 45 MHz and 455 MHz. Adjacent channel selectivity is obtained by using two tuned circuits, a 4-pole 45 MHz crystal filter and a 455 MHz ceramic filter.

All receiver circuitry except the synthesizer is located on the transmitter/receiver board. The receiver consists of:

- Receiver Front End
- L.O. Buffer and Filter
- 45 MHz 1st Mixer
- IF Buffer and Amplifier
- 2nd Mixer and Oscillator
- 455 kHz 2nd IF circuitry with FM Detector and Squelch
- Audio PA Circuitry

RECEIVER FRONT END

An RF signal from the antenna is coupled through J601, Tx low pass filter, transmit T/R switch, a 4-pole bandpass filter (L401-L404) to gate 1 of RF preamplifier Q401. Q401 is a high gain low noise dual gate FET. The output of Q401 is coupled through an additional 2-pole filter (L406, L407), to the input of first mixer Z401. Front end selectivity is provided by these six tuned circuits.

1st MIXER

The 1st mixer is a doubly balanced diode mixer relatively free of intermodulation products. RF from the preamplifier and tuned filters is applied to pin 1 of mixer Z401.

RF injection (181-219 MHz) from the synthesizer VCO is applied to L.O. Buffer Q301 through J351. The input level at J351 is typically +8 dBm (+6 dBm minimum)

at a frequency 45 MHz above the channel receive frequency. R301-R303 and C301 matches the source impedance of Q301 to the VCO output transmit/receive switching circuitry on the synthesizer/interconnect board. The output of the L.O. Buffer is coupled to the mixer through a 3-pole band pass filter (L302-L304) to the 1st mixer L.O. input, Z401-8.

The 45 MHz output of the mixer is coupled to the source input of IF buffer The output of buffer Q501 is coupled through an impedance matching network (C503, C504, R503 and L503) to a 45 mHz 4-pole crystal filter (Z501 and Z502). The highly-selective crystal filter provides the first portion of the receiver IF selectivity. The output of the crystal filter is direct coupled to G1 of IF amplifier Q511. L512 and R511 matches the output of the crystal filter. The biasing on Gate 2 and the drain load determines the gain of the stage. amplifier provides approximately 20 dB of IF gain. The output of Q511 is coupled to the input of IC U501 through an impedance matching network comprised of L515. R521, C514 and C515. Diodes D501 and D502 provide limiting for the 45 MHz signal (1.4 Vpp) to prevent high level overload of U501.

U501 and associated circuitry consists of the 2nd converter/mixer, IF amplifier, FM detector, and squelch circuit. The 45 MHz IF input is applied to pin 16 of U501 and mixed with a 45.455 MHz frequency supplied by crystal oscillator Y501. L513 sets the frequency of Y501. High side injection is used. The output of the internal mixer is amplified and applied to a 6-pole ceramic filter, Z503, which provides the 455 kHz selectivity. The output of the 455 kHz filter is reapplied to U501-5. The 2nd IF signal is amplified/limited and the audio detected by an internal FM quadrature detector. L514 is the quadrature detector coil which controls the phase shift to allow audio detection.

AUDIO AND SQUELCH CIRCUITS

The audio output of U501 is applied to the base of audio buffer Q601. The output of the audio buffer is applied to the Channel Guard Tone/Code Reject filter on the synthesizer/interconnect board, then to audio amplifier U601 through the MONITOR switch, and to the squelch input U501-10.

Squelch Circuit

The squelch circuit operates on the noise components contained in the FM detector audio output. The detected audio is applied to the squelch high pass filter. This filter is formed with the

internal operational amplifier and feedback circuit. Thus the filtered noise in the 6-8 kHz frequency band is applied to the squelch detector consisting of squelch adjust R607, R629, R608, C606, C607, C621 and diode D601. As the noise increases in magnitude in a negative direction, negative spikes cause D601 to conduct, providing a noise level controlled DC input to the internal squelch circuitry of U501. The charge on C607 varies with the average noise level through D601. This output is reapplied to the Schmidt trigger in U501. Schmidt trigger output controls CAS buffer Q602. About 4 dB of hysteresis is present in the Schmidt trigger to prevent chatter due to weak signals. Q602 provides drive to operate an optional channel busy light or external relay control. Squelch sensitivity is adjusted by R607 while R629 provides temperature compensation.

Audio Circuits

Detected audio from audio buffer Q601 is applied to the Channel Guard Tone/Code Reject filter on the synthesizer/interconnect board and returned as filtered volume squelch high through P903-7. Filtered audio is then applied to audio amplifier U601 through MONITOR switch S602 and VOLUME control R617. R618 and C615 provide de-emphasis. A+ is applied to U601 through S617. The RX MUTE line is high when a message is received and accompanied by a correct Channel Guard Tone/Code, keeping audio switch Q603 turned off. This enables audio amplifier U601 which provides up to 3 watts of audio output power into a 4 ohm speaker. The feedback loop consisting of R615, R616, and C611 determine the amplifier closed loop gain. R614 and C612 provide the high audio frequency roll-off above 6 kHz.

The audio amplifier is muted (switched off) when $\overline{\text{RX}}$ MUTE is low. When this occurs (no messages being received) audio switch Q603 is turned on, applying approximately 2 volts to the reference input of audio amplifier U601. This turns Q601 off causing it's output to be grounded.

Monitor

When the MONITOR switch is pressed, detected audio from audio buffer Q601 is applied directly to the audio amplifier through S602-5 and R617, bypassing the Channel Guard Tone/Code Reject Filter. S602 also opens the RX MUTE line to Q603, causing it to be turned off and allowing audio amplifier U601 to operate. The detected audio is amplified and applied to the speaker. Channel Guard Codes/Tones may be audible when present.

MODE A/B

Mode A/B Switch S601 doubles the channel selection capability of the radio by controlling the 8.5V CONT line applied to the Mode A/B input of the microcomputer. 8.5V CONT is applied to the microcomputer thru P912 in Mode B and removed in Mode A. Mode B is indicated

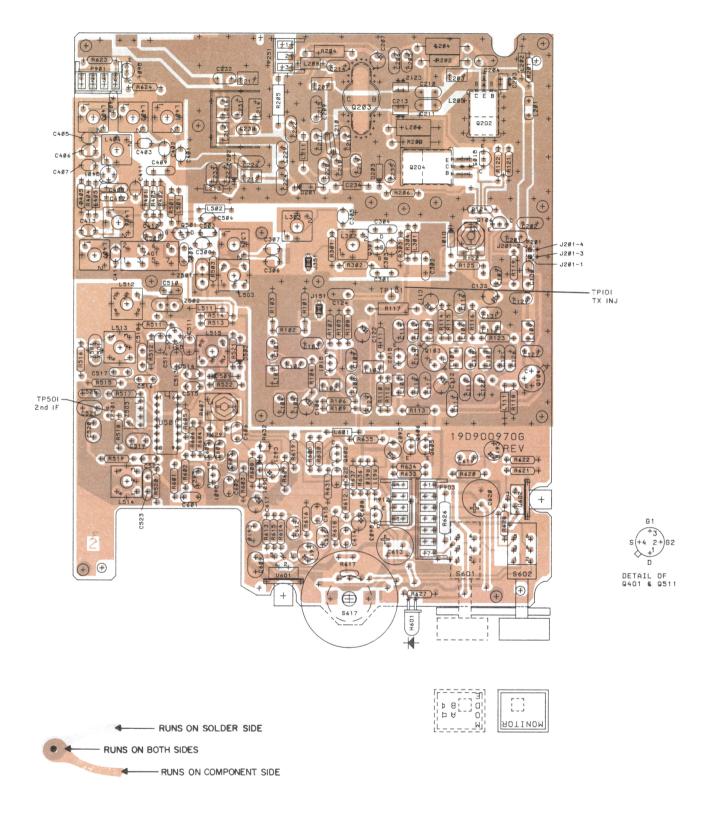
on the 7 segment display by an illuminated decimal point.

8.5 VOLT REGULATOR

8.5 Volt regulator U602 receives switched A+ from S617 and P903-6 and provides regulated 8.5 Volts to the radio. Switched A+ is available from S617.

GENERAL ELECTRIC COMPANY • MOBILE COMMUNICATIONS DIVISION WORLD HEADQUARTERS • LYNCHBURG, VIRGINIA 24502 U.S.A.





OUTLINE DIAGRAM

150—174 MHz, 40 WATT WIDEBAND TRANSMIT/RECEIVE BOARD

(19D900972, Rev. 6) (19A703234, Sh. 1, Rev. 2) (19A703234, Sh. 2, Rev. 3)

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NOTES & CHARTS	SHEET
TRANSMITTER	2
FUNCTION	CPNT SERIES
EXCITER TX PWR AMP TX 0.5V SWITCH	100 200 600
RECEIVER	3
FUNCTION	SERIES
1ST LO INJECTION RF/MIXER 1ST IF	350 400 500
RECEIVER/SYSTEM	4 CPNT
FUNCTION	SERIES
2ND IF AUDIO/SQUELCH/SYSTEM	500 600

LBI31243

NOTES

A PART OF PWB.



VALUE OF R621 DEPENDS ON COLOR CODE ON U602.

U602 COLOR CODE	R621 VALUE
BROWN	OMIT R621
RED	270
ORANGE	100
YELLOW	47
GREEN	22
BLUE	6.8

A SWITCH PRESENT ON 00264,66 ONLT.



A VOLTAGE READINGS:

ALL VOLTAGES ARE TYPICAL. VOLTAGES ARE MEASURED WITH A 20,000 OHM PER VOLT METER, REFERENCE TO A-, UNLESS OTHERWISE INDICATED.

SHEET 2: ALL VOLTAGES ARE DC ALL VOLTAGES ARE IN THE TRANSMIT CONDITION.

SHEET 3: ALL VOLTAGES ARE DC

SHEET 4:
ALL VOLTAGES ARE DC
VOLTAGES AT USO1 AND U601 ARE MEASURED WITH
1 M OHM DC VOLTMETER.
DIFFERENCE IN VOLTAGE READINGS AT USO1-5 & 6
SHOULD BE LESS THAN 6 MYDC.
S - SQUELCHED RECEIVER
US - UNSQUELCHED RECEIVER

A CALLED FOR AT HIGHER ASM.

△ C(OMPONENT IDENTIF	ICATION CHART
	970G1	970G3
PART	150-174 MHZ	136-153 MHZ
C119	182	27₽
C120	22=	27 p
C129	12p	18P
C130	39P	100p
C201	18P	24p
C202	1 8 P	24P
C203	180p	220p
C210	56₽	75 P
C211	56P	75₽
C213	150p	220P
C219	15P	20₽
C231	24P	27P
C232	1 0 P	8 P
C303	3.3P	4.7P
C306	4.7P	5.6P
C307	1.5p	1.0P
C308	5.6	0.2₽
C309	22 P	5.6P
C403	6.8p	10P
C404	56P	68P
C405	5.6P	10P
C406	2.7p	1.8=
C407	1.5P	3.3P
C411	2.2P	5.6₽
C412	150P	27 p
C414	6.8p	5.6P
R118	15	10

P		
	REV.	
MODEL NO.	LETTER	FREG RANGE
PL19D900970G1	A	
PL19D901002G2		150-174 MHZ
PL19D901002G4		
PL19D900970G3	A	
PL19D901002G5		136-153 MHZ
PL19D901002G6		

ALL RESISTORS ARE 1/4 WATT UNLESS OTHERWISE SPECIFIED.
RESISTOR VALUES IN A UNLESS FOLLOWED BY MULTIPLIER & OR M.
CAPACITOR VALUES IN F UNLESS FOLLOWED BY MULTIPLIER DA OR P.
INDUCTANCE VALUES IN H UNLESS FOLLOWED BY MULTIPLIER M OR P.

(19D900974, Sh. 1, Rev. 6)

SCHEMATIC DIAGRAM NOTES

136-174 MHz TRANSMIT/RECEIVE BOARD

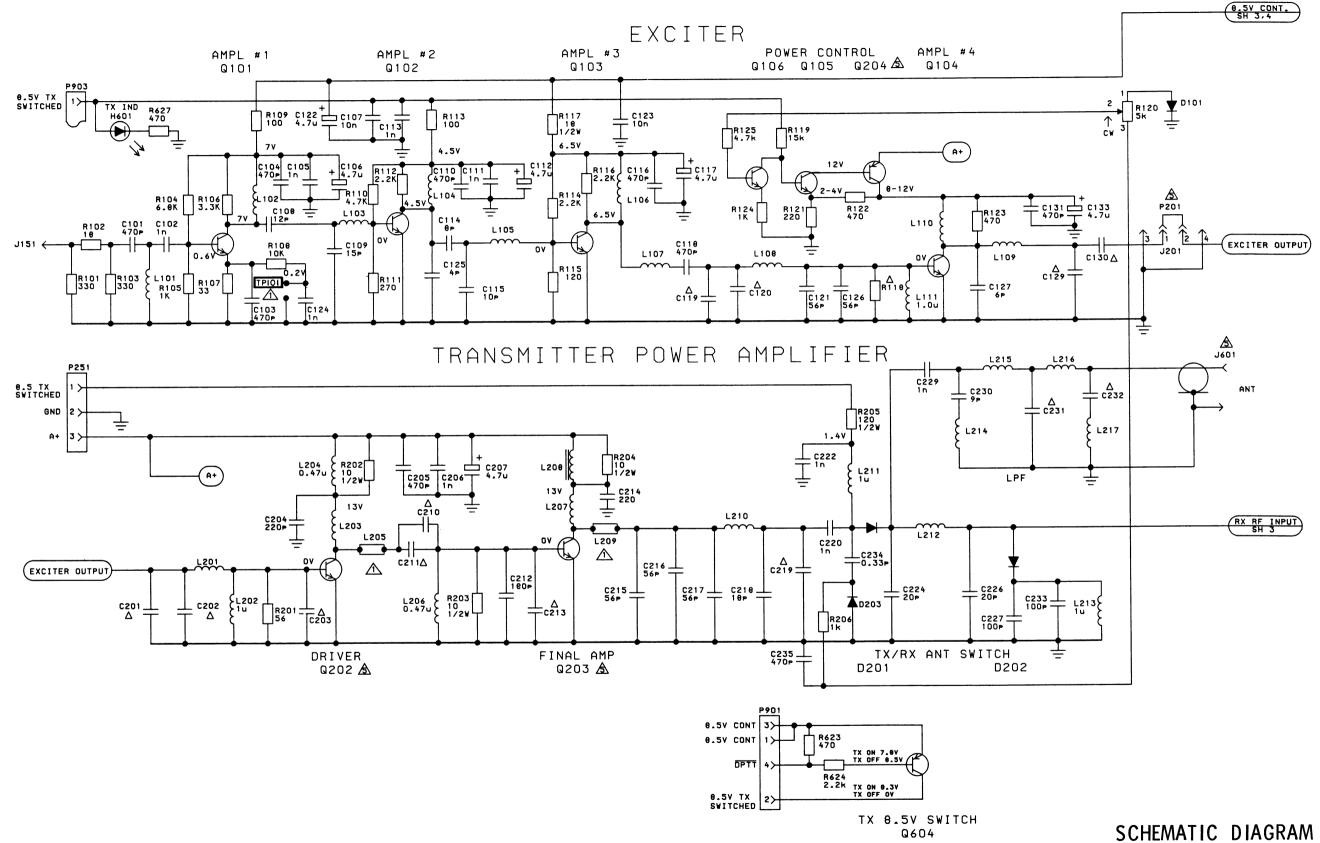
Issue 2 7

PARTS LIST

136-174 MHz
40 WATT TRANSMIT/RECEIVE ASSEMBLY
(WIDEBAND)
19D901002G2 STD 150-174 MHz
19D901002G4 MODE SWITCH 150-174 MHz
19D901002G5 STD 136-153 MHz
19D901002G6 MODE SWITCH 136-153 MHz
ISSUE 3

GE PART NO. SYMBOL DESCRIPTION TRANSMIT/RECEIVE BOARD
19D900970G1 STD - REV A
19D900970G3 MODE SWITCH - REV A A 1 EXCITER Ceramic: 470 pF $\pm 20\%$, 1000 VDCW; sim to Type JF Discap. 19A701602P13 C102 19A701602P20 Ceramic: 1000 pF \pm 10%, 1000 VDCW. Ceramic: 470 pF $\pm 20\%$, 1000 VDCW; sim to Type JF Discap. 19A701602P13 and C104 C105 19A701602P20 Ceramic: 1000 pF \pm 10%, 1000 VDCW. Electrolytic: 4.7 uF -10+50% tol, 50 VDCW; sim to Panasonic LS Series. C106 19A703314P9 C107 19A700234P7 Polyester: 0.01 uF ±10%, 50 VDCW. Ceramic, disc: 12 pF \pm 5%, 500 VDCW, temp coef 0 PPM \pm 30. C108 19A701624P10 Ceramic, disc: 15 pF \pm 5%, 500 VDCW, temp coef 0 PPM \pm 30. 19A701624P12 19A701602P13 Ceramic: 470 pF \pm 20%, 1000 VDCW; sim to Type JF Discap. C110 C111 19A701602P20 Ceramic: 1000 pF ±10%, 1000 VDCW. C112 19A703314P9 Electrolytic: 4.7 uF -10+50% tol, 50 VDCW; sim to Panasonic LS Series. C113 19A701602P20 Ceramic: 1000 pF ±10%, 1000 VDCW. C114 19A701624P6 Ceramic, disc: 8 pF \pm 0.5 pF, 500 VDCW, temp coef 0 PPM \pm 60. C115 19A701624P8 Ceramic, disc: 10 pF \pm 0.5 pF, 500 VDCW, temp coef 0 PPM \pm 30. Ceramic: 470 pF $\pm 20\%$, 1000 VDCW; sim to Type JF Discap. C116 19A701602P13 Electrolytic: 4.7 uF -10+50% tol, 50 VDCW; sim to Panasonic LS Series. C117 19A703314P9 Ceramic: 470 pF ±20%, 1000 VDCW; sim to Type JF Discap. C118 19A701602P13 Ceramic disc: 18 pF $\pm 5\%$, 500 VDCW, temp coef 0 PPM ± 30 . (Used in $\overline{G}1$). C119A 19A701624P14 Ceramic disc: 27 pF \pm 5%, 500 VDCW, temp coef 0 PPM \pm 30. (Used in \overline{G} 3). C119B 19A701624P18 Ceramic, disc: 22 pF \pm 5%, 500 VDCW, temp coef 0 PPM \pm 30. C120A 19A701624P16 Ceramic, disc: 27 pF ±5%, 500 VDCW, temp coef 0 PPM ±30. 19A701624P18 C120B 19A701624P326 Ceramic, disc: 56 pF \pm 5%, 50 VDCW, temp coef N220 PPM \pm 30. C121 Electrolytic: 4.7 uF -10+50% tol, 50 VDCW; sim to Panasonic LS Series. C122 19A703314P9 C123 19A700234P7 Polyester: 0.01 uF \pm 10%, 50 VDCW. C124 19A701602P20 Ceramic: 1000 pF ±10%, 1000 VDCW. C125 19A701624P2 Ceramic, disc: 4 pF \pm 0.5 pF, 500 VDCW, temp coef 0 PPM \pm 60. C126 19A701624P326 Ceramic, disc: 56 pF \pm 5%, 50 VDCW, temp coef N220 PPM \pm 30. Ceramic, disc: 6 pF ±0.5 pF, 500 VDCW, temp coef 0 PPM ±60. C127 19A701624P4 Ceramic, disc: 12 pF \pm 5%, 500 VDCW, temp coef 0 PPM \pm 30. (Used in G1). 19A701624P10

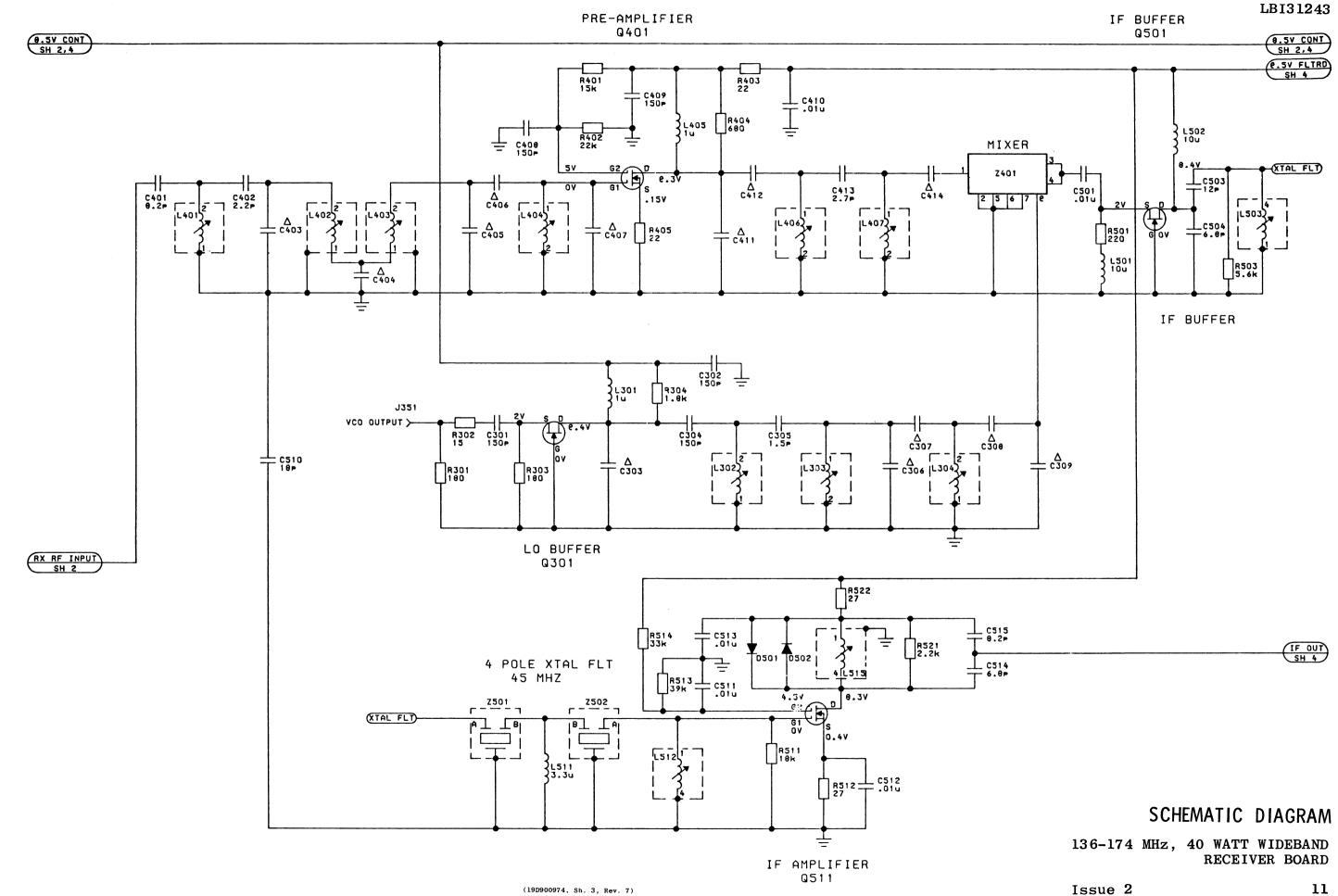
SYMBOL	GE PART NO.	DESCRIPTION	SYMBOL	GE PART NO.	DESCRIPTION
C129	19A701624P14	Ceramic, disc: 18 pF ±5%, 500 VDCW, temp coef 0 PPM ±30. (Used in G3).	R118	19A700019P13	Deposited carbon: 10 ohms $\pm 5\%$, 1/4 w. (Used in G3).
C130	19A701624P22	Ceramic, disc: 39 pF ±5%, 500 VDCW, temp coef	R119	19A700019P51	Deposited carbon: 15K ohms ±5%, 1/4 w.
2100	104 701 700 04	0 PPM ±30. (Used in GĪ).	R120	19B800784P106	Variable: 5K ohms <u>+</u> 20%, 1/2 w.
C130	19A701602P4	Ceramic: 100 pF ±10%, 1000 VDCW; sim to Radio Materials Type JF Discaps. (Used in G3).	R121	19A700019P29	Deposited carbon: 220 ohms ±5%, 1/4 w.
C131	19A701602P13	Ceramic: 470 pF <u>+</u> 20%, 1000 VDCW; sim to Type JF Discap.	R122 and R123	19A700019P33	Deposited carbon: 470 ohms $\pm 5\%$, 1/4 w.
C133	19A703314P9	Electrolytic: 4.7 uF -10+50% tol, 50 VDCW; sim to Panasonic LS Series.	R124	19A700019P37	Deposited carbon: 1K ohms +5%, 1/4 w.
			R125	19A700019P45	Deposited carbon: 4.7K ohms ±5%, 1/4 w.
D101	19A700028P1	Silicon, fast recovery: fwd current 75mA, 75 PIV; sim to Type 1N4148.	TP101		Part of printed board 19D900969P1.
					POWER AMPLIFIER
J151	19A701883P4	Contact, electrical; sim to AMP 86444-1.			FOWER AMPERIALISM
L101	19B800891P5	Coil, RF: .064 uH; sim to Paul Smith SK-890-1.	C201A	19A701624P14	Ceramic, disc: 18 pF ±5%, 500 VDCW, temp coef 0 PPM ±30.
L102	19B800891P6	Coil, RF: .084 uH; sim to Paul Smith SK-890-1.	C201B	19A701624P17	Ceramic, disc: 24 pF ±5%, 500 VDCW, temp coef 0 PPM ±30.
L103	19B800891P5	Coil, RF: .064 uH; sim to Paul Smith SK-890-1.	C202A	19A701624P14	Ceramic, disc: 18 pF ±5%, 500 VDCW, temp coef
L104	19B800891P6	Coil, RF: .084 uH; sim to Paul Smith SK-890-1.			0 PPM ±30.
L105 L106	19B800891P5 19B800891P6	Coil, RF: .064 uH; sim to Paul Smith SK-890-1. Coil, RF: .084 uH; sim to Paul Smith SK-890-1.	C202B	19A701624P17	Ceramic, disc: 24 pF ±5%, 500 VDCW, temp coef 0 PPM ±30.
L107	19B800890P3	Coil, RF: 11.7 uH ±5%, sim to Paul Smith	C203	19A701413P41	Mica: 180 pF ±5%, 100 VDCW. (Used in G1).
		SK-896-1.	C203	19A701413P44	Mica: 220 pF ±5%, 100 VDCW. (Used in G3).
L108 L109	19B800891P1 19B800891P3	Coil, RF Choke: sim to Paul Smith SK-890-1.	C204	19A701602P10	Ceramic: 220 pF +10%, 1000 VDCW.
L110	198800891P6	Coil, RF Choke; sim to Paul Smith SK890-1. Coil, RF: .084 uH; sim to Paul Smith SK-890-1.	C205	19A701602P13	Ceramic: 470 pF ±20%, 1000 VDCW; sim to Type JF Discap.
L111	19A700024P13	Coil, RF: 1.0 uH ±10%.	C206	19A701602P20	Ceramic: 1000 pF ±10%, 1000 VDCW.
		1	C207	19A703314P9	Electrolytic: 4.7 uF -10+50% tol, 50 VDCW; sim to Panasonic LS Series.
Q101 and Q102	19A702084P1	Silicon, NPN; sim to MPS 2369.	C210 and C211	19A701624P326	Ceramic, disc: 56 pF ±5%, 50 VDCW, temp coef N220 PPM ±30. (Used in G1).
Q103 Q104	19A116868P1 19A700063P1	Silicon, NPN; sim to Type 2N4427.	C210 and C211	19A701624P529	Ceramic, disc: 75 pF ±5%, 500 VDCW, temp coef N470 PPM ±60. (Used in G3).
Q105	19A700023P2	Silicon, NPN; sim to Type 2N3904.	C212	19A701413P41	Mica: 180 pF ±5%, 100 VDCW.
and Q106			C213	19A701413P38	Mica: 150 pF ±5%, 100 VDCW. (Used in G1).
		RESISTORS	C213	19A701413P44	Mica: 220 pF ±5%, 100 VDCW. (Used in G3).
R101	19A700019P31	Deposited carbon: 330 ohms ±5%, 1/4 w.	C214	19A701602P10	Ceramic: 220 pF ±10%, 1000 VDCW.
R102	19A700019P16	Deposited carbon: 18 ohms ±5%, 1/4 w.	C215 thru C217	19A701624P326	Ceramic, disc: 56 pF +5%, 50 VDCW, temp coef N220 PPM +30.
R103 R104	19A700019P31 19A700019P47	Deposited carbon: 330 ohms ±5%, 1/4 w.	C218	19A701624P14	Ceramic disc: 18 pF ±5%, 500 VDCW, temp coef
R105	19A700019P37	Deposited carbon: 6.8K ohms ±5%, 1/4 w. Deposited carbon: 1K ohms ±5%, 1/4 w.	C219	19A701624P12	0 PPM ±30. Ceramic, disc: 15 pF ±5%, 500 VDCW, temp coef
R106	19A700019P43	Deposited carbon: 3.3K ohms ±5%, 1/4 w.	C219	19A701624P15	0 PPM <u>+</u> 30. (Used in GĪ). Ceramic disc: 20 pF <u>+</u> 5%, 500 VDCW, temp coef
R107	19A700019P19	Deposited carbon: 33 ohms ±5%, 1/4 w.			0 PPM ±30. (Used in G3).
R108 R109	19A700019P49 19A700019P25	Deposited carbon: 10K ohms ±5%, 1/4 w.	C220 C222	19A701602P20 19A701602P20	Ceramic: 1000 pF ±10%, 1000 vDCW. Ceramic: 1000 pF ±10%, 1000 vDCW.
R110	19A700019P25	Deposited carbon: 100 ohms ±5%, 1/4 w. Deposited carbon: 4.7K ohms +5%, 1/4 w.	C222	19A701602P20	Ceramic, disc: 20 pF ±5%, 500 VDCW, temp coef
R111	19A700019P30	Deposited carbon: 270 ohms ±5%, 1/4 w.		10010210	0 PPM ±30.
R112	19A700019P41	Deposited carbon: 2.2K ohms ±5%, 1/4 w.	C226	19A701624P15	Ceramic, disc: 20 pF ±5%, 500 VDCW, temp coef 0 PPM ±30.
R113	19A700019P25	Deposited carbon: 100 ohms ±5%, 1/4 w.	C227	19A701602P4	Ceramic: 100 pF ±10%, 1000 VDCW; sim to Radio Materials Type JF Discaps.
R114	19A700019P41	Deposited carbon: 2.2K ohms ±5%, 1/4 w.	C229	19A701602P20	Ceramic: 1000 pF +10%, 1000 VDCW.
R115	19A700019P26	Deposited carbon: 120 ohms ±5%, 1/4 w.	C230	19A701624P7	Ceramic, disc: 9 pF ±0.5 pF, 500 VDCW, temp coef
R116	19A700019P41	Deposited carbon: 2.2K ohms ±5%, 1/4 w.		101501601715	0 PPM <u>+</u> 60 PPM.
R117 R118	19A700113P21 19A700019P15	Composition: 18 ohms ±5%, 1/2 w. Deposited carbon: 15 ohms ±5%, 1/4 w. (Used in	C231	19A701624P17	Ceramic, disc: 24 pF ±5%, 500 VDCW, temp coef 0 PPM ±30. (Used in GI).
		GI). (oded in	C231	19A701624P18	Ceramic, disc: 27 pF ±5%, 500 VDCW, temp coef 0 PPM ±30. (Used in G3).
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136-174 MHz, 40 WATT WIDEBAND TRANSMITTER BOARD

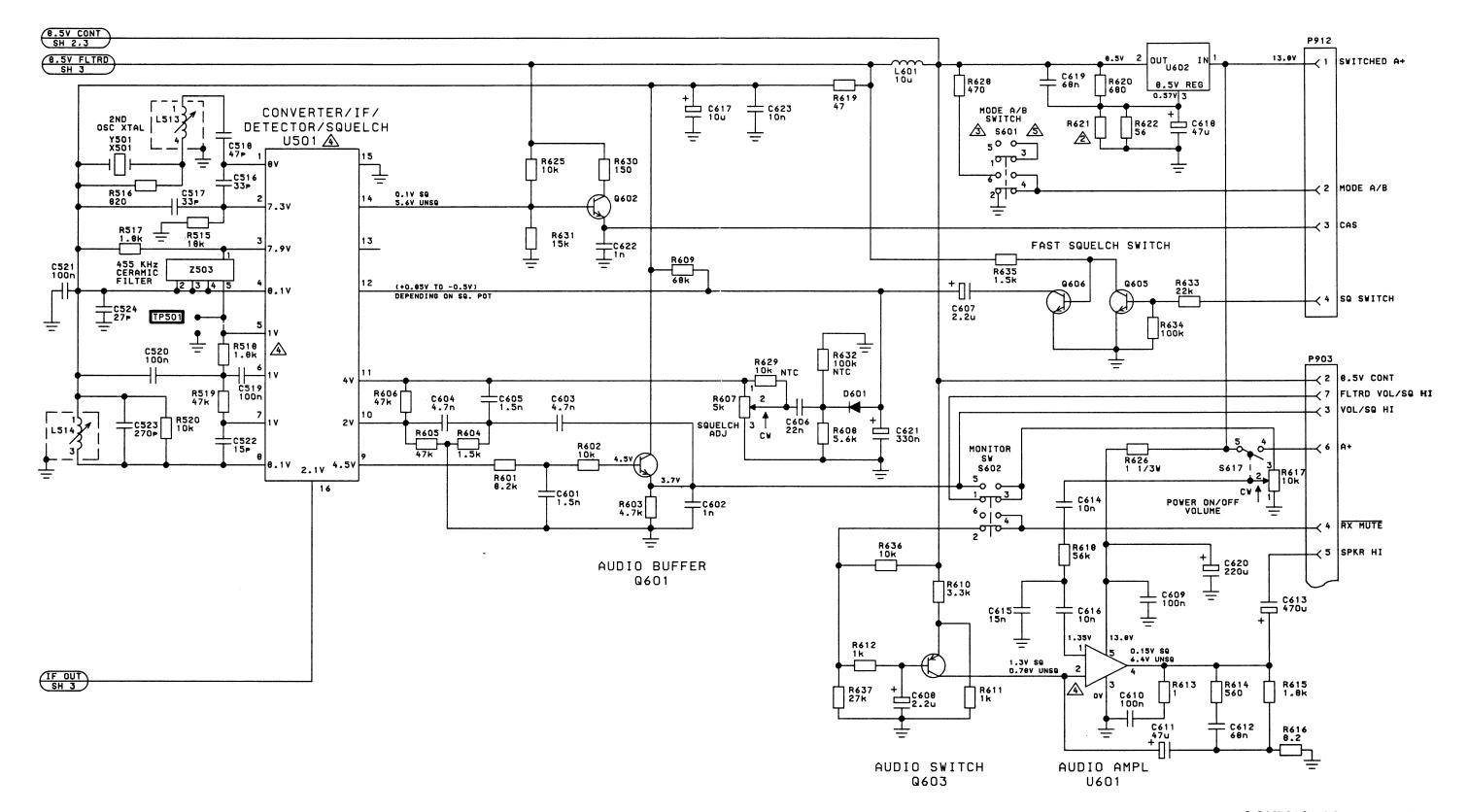
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SYMBOL	GE PART NO.	DESCRIPTION	SYMBOL	GE PART NO.	DESCRIPTION	SYMBOL	GE PART NO.	DESCRIPTION
C232	19A701624P8	Ceramic, disc: 10 pF ±0.5 pF, 500 VDCW, temp				C410	19A700234P7	Polyester: 0.01 uF +10%, 50 VDCW.
C232	19A701624P6	coef 0 PPM ±30. (Used in G1). Ceramic, disc: 8 pF ±5%, 500 VDCW, temp coef 0 PPM +60. (Used in G3).			RECEIVER VCO INJECTION	C411	19A700235P5	Ceramic: 2.2 pF ±0.25 pF, 50 VDCW, temp coef -150 PPM. (Used in G1).
C233	19A701602P4	Ceramic: 100 pF ±10%, 1000 VDCW; sim to Radio Materials Type JF Discaps.	C301 and	19A700235P27		C411	19A700235P10	Ceramic: 5.6 pF ±0.25 pF, 50 VDCW, temp coef -150 PPM. (Used in G3).
C234	19A700013P7	Phenolic: 0.33 pF ±5%, 500 VDCW.	C302			C412	19A700235P27	Ceramic: 150 pF <u>+</u> 5%, 50 VDCW. (Used in G1).
C235	19A701602P13	Ceramic: 470 pF ±20%, 1000 VDCW; sim to Type JF Discap.	C303	19A700235P7	Ceramic: 3.3 pF ±0.25 pF, 50 VDCW, temp coef N150 PPM. (Used in G1).	C412	19A700235P18	Ceramic: 27 pF ±5%, 50 VDCW. (Used in G3).
			C303	19A700235P9	Ceramic: 4.7 pF +0.25 pF, 50 VDCW, temp coef -150 PPM. (Used in G3).	C413	19A700235P6	Ceramic: 2.7 pF ±0.25 pF, 50 VDCW, temp coef N150 PPM.
D201	19J706892P2	Silicon.	C304	19A700235P27	Ceramic: 150 pF <u>+</u> 5%, 50 VDCW.	C414	19A700235P11	Ceramic: 6.8 pF <u>+</u> 0.25 pF, 50 VDCW. (Used in G1).
and D202	100 10000212	J. T. Cont.	C305	19A700235P3	Ceramic: 1.5 pF ±0.25 pF, 50 VDCW, temp coef -150 PPM.	C414	19A700235P10	Ceramic: 5.6 pF +0.25 pF, 50 VDCW, temp coef N150 PPM. (Used in G3).
D203	19A700047P3	Silicon: 100 mW; sim to 1N6263.	C306	19A700235P9	Ceramic: 4.7 pF +0.25 pF, 50 VDCW, temp coef -150 PPM. (Used in G1).			
J201	10470204901		C306	19A700235P10	Ceramic: 5.6 pF \pm 0.25 pF, 50 VDCW, temp coef \pm 150 PPM. (Used in G3).	L401 thru	19B800965P323	Coil, RF: variable; sim to Paul Smith SK-767-2.
3201	19A703248P1	Contact, electrical. (Quantity 4).	C307	19A700235P3	Ceramic: 1.5 pF +0.25 pF, 50 VDCW, temp coef	L404 L405	19A700024P13	Coil, RF: 1.0 uH +10%.
L201	198800890P6	Coll DE: 14 7 TH 159 TH 15 TH	C307	19A700235P1	Ceramic: 1 pF +0.25 pF, 50 VDCW, temp coef	L406	19B800965P323	Coil, RF: variable; sim to Paul Smith SK-767-2.
L201	19800089076	Coil, RF: 14.7 nH ±5%, sim to Paul Smith SK-891-1.	C308	19A700235P10	-150 PPM. (Used in G3).	and L407		
L202	19A700024P13	Coil, RF: 1.0 uH ±10%.	C308	19A700235P10	Ceramic: 5.6 pF ±0.25 pF, 50 VDCW. (Used in G1) Ceramic: 8.2 pF ±0.25 pF, 50 VDCW. (Used in G3)			
L203	198800891P3	Coil, RF Choke; sim to Paul Smith SK890-1.	C309	19A700235P17	Ceramic: 22 pF ±5%, 50 VDCW. (Used in G1).	Q401	19A700075P1	N-CHANNEL, field effect. (MOS DUAL GATE).
L204 L205	19A700000P8	Coil, RF: 470 nH ±12%; sim to Jeffers 4411-4K. Part of Printed Board 19D900969P1.	C309	19A700235P10	Ceramic: 5.6 pF ±0.25 pF, 50 VDCW. (Used in G3)			RESISTORS
L205	19A700000P8	Coil, RF: 470 nH +12%; sim to Jeffers 4411-4K.				R401	19A700019P51	Deposited carbon: 15K ohms ±5%, 1/4 w.
L207	19B800891P2	Coil, RF Choke: sim to Paul Smith SK-890-1.	J351	19A701883P4	Contact, electrical; sim to AMP 86444-1.	R402	19A700019P53	Deposited carbon: 22K ohms ±5%, 1/4 w.
L208	19A701091G1	Coil.				R403	19A700019P17	Deposited carbon: 22 ohms ±5%, 1/4 w.
L209		Part of Printed Board 19D900969P1.	L301	19A700024P13	Coil, RF: 1.0 uH +10%.	R404	19A700019P35	Deposited carbon: 680 ohms ±5%, 1/4 w.
L210	19A701421P6	Coil. (Used in G1).	L302	19B800965P323	Coil, RF: variable; sim to Paul Smith SK-767-2.	R405	19A700019P17	Deposited carbon: 22 ohms ±5%, 1/4 w.
L210	19A701421P2	Coil. (Used in G3).	thru L304	100000001020	corr, Mr. variable, Sim to Faul Smith Sk-767-2.			
L211	19A700024P13	Coil, RF: 1.0 uH ±10%.				Z401	19B801025P1	Balanced Mixer (Double); sim to Mini-Circuits
L212	19B800891P4	Coil, RF Choke: sim to Paul Smith SK-890-1. (Used in G1).	Q301	19A700060P2	N Type, field effect.			SBL-1.
L212	19B800891P5	Coil, RF: 0.64 uH; sim to Paul Smith SK-890-1. (Used in G3).						IF
L213	19A700024P13	Coil, RF: 1.0 uH +10%.	R301	19A700019P28	Deposited carbon: 180 ohms ±5%, 1/4 w.			CAPACITORS
L214	19B800891P2	Coil, RF Choke: sim to Paul Smith SK-890-1.	R302	19A700019P15	Deposited carbon: 15 ohms $\pm 5\%$, 1/4 w.	C501	19A700234P7	Polyester: 0.01 uF ±10%, 50 VDCW.
		(Used in G1).	R303	19A700019P28	Deposited carbon: 180 ohms ±5%, 1/4 w.	C503	19A700235P14	Ceramic, disc: 12 pF ±5%, 50 VDCW.
L214	19B800891P3	Coil, RF Choke: sim to Paul Smith SK-890-1. (Used in G3).	R304	19A700019P40	Deposited carbon: 1.8K ohms ±5%, 1/4 w.	C504	19A700235P11	Ceramic: 6.8 pF +0.25 pF, 50 VDCW.
L215	19B800891P5	Coil, RF: .064 uH; sim to Paul Smith SK-890-1.			RECEIVER FRONT END	C510	19A700235P16	Ceramic: 18 pF ±5%, 50 VDCW.
and L216 L217	19B800891P2	Coil, RF Choke: sim to Paul Smith SK-890-1.			0.0107500	C511 thru C513	19A700234P7	Polyester: 0.01 uF ±10%, 50 VDCW.
		(Used in G1).	C401	19A700235P12		C514	19A700235P11	Ceramic: 6.8 pF ±0.25 pF, 50 VDCW.
L217	19B800891P3	Coil, RF Choke: sim to Paul Smith Sk-890-1. (Used in G3).	C401	19A700235P12	Ceramic: 8.2 pF ±0.25 pF, 50 VDCW.	C515	19A700235P12	Ceramic: 8.2 pF ±0.25 pF, 50 VDCW.
					Ceramic: 2.2 pF ±0.25 pF, 50 VDCW, temp coef -150 PPM.	C516 and	19A700235P19	Ceramic: 33 pF ±5%, temp coef -150 PPM.
P201	19A702104P1	Receptacle: 2 position, shorting, rated at	C403	19A700235P11 19A700235P13	Ceramic: 6.8 pF +5%, 50 VDCW. (Used in G1).	C517	101500005001	0
		3 amps; sim to Berg 65474-002.	C404	19A700235P13	Ceramic: 10 pF ±5%, 50 VDCW. (Used in G3). Ceramic: 56 pF ±5%, 50 VDCW. (Used in G1).	C518 C519	19A700235P21 19A702250P113	Ceramic: 47 pF ±5%, 50 VDCW. Polyester: .1 uF ±10%, 50 VDCW.
P251	19A116659P1	Connector, printed wiring: 3 contacts rated at 5 amps; sim to Molex 09-52-3032.	C404	19A700235P23	Ceramic: 68 pF ±5%, 50 VDCW. (Used in G3).	thru C521	1047022307113	rolyester1 ur +10%, 50 vbcw.
			C405	19A700235P10	Ceramic: 5.6 pF ±0.25 pF, 50 VDCW. (Used in G1)	C522	19A700235P15	Ceramic: 15 pF +5%, 50 VDCW.
R201	19A700019P22		C405	19A700235P13	Ceramic: 10 pF ±5%, 50 VDCW. (Used in G3).	C523	19A700235P30	Ceramic: 270 pF ±5%, 50 VDCW.
R201	19A700013P22	Deposited carbon: 56 ohms \pm 5%, 1/4 w. Composition: 10 ohms \pm 5%, 1/2 w.	C406	19A700235P6	Ceramic: 2.7 pF ±0.25 pF, 50 VDCW, temp coef	C524	19A700235P18	Ceramic, disc: 27 pF ±5%, 50 VDCW.
thru R204	104700113113	Composition. To onus 10s, 1/2 w.	C406	19A700235P4	N150 PPM. (Used in G1).			
R205	19A700113P41	Composition: 120 ohms ±5%, 1/2 w.	1	-011.0020074	Ceramic: 1.8 pF ±0.25 pF, 50 VDCW, temp coef N150 PPM. (Used in G3).	D501	19A700028P1	Silicon, fast recovery: fwd current 75 mA,
R206	19A700019P37	Deposited carbon: 1K ohms ±5%, 1/4 w.	C407	19A700235P3	Ceramic: 1.5 pF +0.25 pF, 50 VDCW, temp coef -150 PPM. (Used in G1).	and D502		75 PIV; sim to Type IN4148.
		1	C407	19A700235P7	Ceramic: 3.3 pF +0.25 pF, 50 VDCW, temp coef N150 PPM. (Used in G3).			
			C408 and C409	19A700235P27	Ceramic: 150 pF ±5%, 50 VDCW.	L501 and L502	19A700024P25	Coil, RF: 10.0 uH <u>+</u> 10%, 3.70 ohms DC res max.
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SYMBOL	GE PART NO.	DESCRIPTION	SYMBOL	GE PART NO.	DESCRIPTION	SYMBOL	GE PART NO.	DESCRIPTION
L503	19A703311P2	Coil, RF: sim to TOKO AMERICA KON-K6672BA.	C613	19A701225P8	Electrolytic: 470 uF -10+75%, 16 VDCW; sim to	R621C	19A700019P21	Deposited carbon: 47 ohms ±5%, 1/4 w.
L511	19A700024P19	Coil, RF: 3.3 uH ±10%.			Sprague 5002D477-G016DGIC.	R621D	19A700019P17	Deposited carbon: 22 ohms ±5%, 1/4 w.
L512	19A703311P2	Coil, RF: sim to TOKO AMERICA KON-K6672BA.	C614	19A700234P7	Polyester: 0.01 uF ±10%, 50 VDCW.	R621E	19A700019P11	Deposited carbon: 6.8 ohms $\pm 5\%$, 1/4 w.
L513	19A703311P1	Coil, RF: sim to TOKO American KON-K6572BA.	C615	19A700234P8	Polyester: .015 uF ±10%, 50 VDCW; sim to NISSEI AMXV or AMZV.	R622	19A700019P22	Deposited carbon: 56 ohms $\pm 5\%$, 1/4 w.
L514	19B801023P1	Coil, RF: 450 uH ±6%, sim to TOKO AMERICAN	C616	19A700234P7	Polyester: 0.01 uF ±10%, 50 VDCW.	R623	19A700019P33	Deposited carbon: 470 ohms ±5%, 1/4 w.
		124LN-A064HM.	C617	19A703314P10	Electrolytic: 10 uF -10+50% tol, 50 VDCW; sim to	R624	19A700019P41	Deposited carbon: 2.2K ohms ±5%, 1/4 w.
L515	19A703311P1	Coil, RF: sim to TOKO American KON-K6572BA.	C618	19A703314P4	Panasonic LS Series. Electrolytic: 47 uF -10+50% tol, 16 VDCW; sim to	R625	19A700019P49	Deposited carbon: 10K ohms ±5%, 1/4 w.
			C010	19A703314P4	Panasonic LS Series.	R626	19A700018P1	Deposited carbon: 1 ohm ±5%, 1/3 w.
Q501	19A700060P2	N Type, field effect.	C619	19A702250P112	Polyester: .068 uF ±10%, 50 VDCW; sim to NISSEI TYPE AMZ.	R627 and	19A700019P33	Deposited carbon: 470 ohms ±5%, 1/4 w.
Q511	19A700075P1	N-CHANNEL, field effect. (MOS DUAL GATE).	C620	19A701225P3	Electrolytic: 220 uF, -10+50%, 25 VDCW.	R628		
		RESISTORS	C621	19A701534P12	Tantalum: .33 uF ±20%, 35 VDCW.	R629	5490828P9	Thermal: 10K ohms ±10%; sim to Carborundum 551J-8.
R501	19A700019P29	Deposited carbon: 220 ohms +5%, 1/4 w.	C622	19A700234P1	Polyester: 1000 pF +10%, 50 VDCW.	R630	19A700019P27	Deposited carbon: 150 ohms ±5%, 1/4 w.
R503	19A700019P46	Deposited carbon: 5.6K ohms ±5%, 1/4 w.	C623	19A700234P7	Polyester: 0.01 uF +10%, 50 VDCW.	R631	19A700019P51	Deposited carbon: 15K ohms ±5%, 1/4 w.
R511	19A700019P52	Deposited carbon: 18K ohms ±5%, 1/4 w.			102,000011 0001 01 <u>1</u> 200, 00 12011	R632	19A702161P2	Composition: 12K ohms ±5%, 1/4 w.
R512	19A700019P18	Deposited carbon: 27 ohms +5%, 1/4 w.				R633	19A700019P53	Deposited carbon: 22K ohms ±5%, 1/4 w.
R513	19A700019P56	Deposited carbon: 39K ohms +5%, 1/4 w.	D601	19A700028P1	Silicon, fast recovery: fwd current 75 mA, 75 PIV; sim to Type 1N4148.	R634	19A700019P61	Deposited carbon: 0.1M ohms ±5%, 1/4 w.
R514	19A700019P55	Deposited carbon: 33K ohms +5%, 1/4 w.				R635	19A700019P39	Deposited carbon: 1.5K ohms ±5%, 1/4 w.
R515	19A700019P52	Deposited carbon: 18K ohms +5%, 1/4 w.				R636	19A700019P49	Deposited carbon: 10K ohms ±5%, 1/4 w.
R516	19A700019P36	Deposited carbon: 820 ohms ±5%, 1/4 w.	H601	19A134354P1	Diode, optoelectronic: red; sim to Hewlett Packard 5082-4655.	R637	19A700019P54	Deposited carbon: 27K ohms ±5%, 1/4 w.
R517	19A700019P40	Deposited carbon: 1.8K ohms +5%, 1/4 w.		i				
and R518								
R519	19A700019P57	Deposited carbon: 47K ohms ±5%, 1/4 w.	L601	19A700024P25	Coil, RF: 10.0 uH ±10%.	8602	19B800563P3	Push: DPDT, contacts rated 15 mA at 130 VDC; sim to IEEE/SCHADOW 51203.
R520	19A700019P49	Deposited carbon: 10K ohms ±5%, 1/4 w.				8617		(Part of R617).
R521	19A700019P41	Deposited carbon: 2.2K ohms +5%, 1/4 w.	Q601	19A700023P2	Silicon, NPN; sim to Type 2N3904.			ANTENNA ATTENNA ATTENNA
R522	19A700019P18	Deposited carbon: 27 ohms ±5%, 1/4 w.	and Q602			,,,,,	10150100001	
			Q603	19A700022P2	Silicon, PNP; sim to Type 2N3906.	U601 U602	19A701830P1 19A138414G1	Linear, Audio AMPLIFIER; sim to TDA 2003.
			Q604	19A134960P1	Silicon, PNP; sim to Type 2N4403.	0602	19413641461	Regulator: 8.5 V.
U501	19A701780P1	Linear: IF AMPLIFIER AND DETECTOR.	Q605	19A700023P2	Silicon, PNP; sim to Type 2N3906.			INTERCONNECT
			and Q606					
X501	19A702742P1	Crystal socket (Quantity 2).				P901	19A116659P15	Connector, printed wiring: 4 contacts rated at
			R601	19A700019P48	Deposited carbon: 8.2K ohms ±5%, 1/4 w.	1	10	5 amps; sim to Molex 09-52-3042.
Y501	19B233066G8	Crystal: freq range 44 to 58 MHz.	R602	19A700019P49	Deposited carbon: 10K ohms ±5%, 1/4 w.	P903	19A116659P83	Connector, printed wiring: 7 contacts rated at 5 amps; sim to Molex 09-52-3072 SPECIAL.
1301	19823300000	Crystal. freq range 44 to 30 mmz.	R603	19A700019P45	Deposited carbon: 4.7K ohms ±5%, 1/4 w.	P912	19A116659P15	Connector, printed wiring: 4 contacts rated at
			R604	19A700019P39	Deposited carbon: 1.5K ohms ±5%, 1/4 w.			5 amps; sim to Molex 09-52-3042.
Z501A	19A702166G2	Crystal pair, quartz: 45 MHz reference frequency	R605	19A700019P57	Deposited carbon: 47K ohms ±5%, 1/4 w.			
Z501B		(Part of Z501A).	and R606			P201	19A702104P1	Receptacle: 2 positions, shorting, rated @
Z503	19B801021P2	Bandpass filter: 455 kHz ±1.5; sim to Murata CFW-455E.	R607	19B800784P106	Variable: 5K ohms ±20%, 1/2 w.			3 amps; sim to Berg 65474-002.
			R608	19A700019P46	Deposited carbon: 5.6K ohms ±5%, 1/4 w.			TRANSISTORS
		RECEIVE AUDIO	R609	19A700019P59	Deposited carbon: 68K ohms ±5%, 1/4 w.	Q202	19A701891P2	Silicon, NPN, UHF Amplifier: 15 watt, 12.5 v.
			R610	19A700019P43	Deposited carbon: 3.3K ohms ±5%, 1/4 w.	Q203	19A134340P4	Silicon, NPN, UHF Amplifier: 45 watt.
C601	19A700234P2	Polyester: 1500 pF <u>+</u> 10%, 50 VDCW.	R611	19A700019P37	Deposited carbon: 1K ohms ±5%, 1/4 w.	Q204	19A116375P1	Silicon, NPN.
C602	19A700234P1	Polyester: 1000 pF ±10%, 50 VDCW.	and R612				1	
C603	19A700234P5	Polyester: 4700 pF ±10%, 50 VDCW.	R613	19A700019P1	Deposited carbon: 1 ohms ±5%, 1/4 w.	S601	19B800563P1	Push, DPDT, 1 station, alternate action; sim to
and C604			R614	19A700019P34	Deposited carbon: 560 ohms ±5%, 1/4 w.	1	1555555557	IEEE/Schadow 51281 (F2UEE).
C605	19A700234P2	Polyester: 1500 pF <u>+</u> 10%, 50 VDCW.	R615	19A700019P40	Deposited carbon: 1.8K ohms ±5%, 1/4 w.	1	1	MISCELLANEOUS
C606	19A700234P9	Polyester: 0.022 uF ±10%, 50 VDCW.	R616	19A700019P12	Deposited carbon: 8.2 ohms ±5%, 1/4 w.		19B800853P1	Shield, filter. (Located at L216).
C607 and	19A701534P5	Tantalum: 2.2 uF ±20%, 35 VDCW.	R617	19A703313P1	Variable: 10K ohms <u>+</u> 20%, .1 watt.		19A701332P4	Insulator, washer: nylon. (Used with Q103).
C608			R618	19A700019P58	Deposited carbon: 56K ohms ±5%, 1/4 w.		19B232901P1	Support. (Mounts U601 & U602).
C609 and	19A702250P113	Polyester: .1 uF ±10%, 50 VDCW.	R619	19A700019P21	Deposited carbon: 47 ohms ±5%, 1/4 w.		19A700115P3	Insulator, plate. (Used with Q204 and U602).
C610			R620	19A700019P35	Deposited carbon: 680 ohms ±5%, 1/4 w.	1	19A700068P1	Insulator, bushing. (Used with U602).
C611	19A701534P9	Tantalum: 47 uF ±20%, 6.3 VDCW.	R621A	19A700019P30	Deposited carbon: 270 ohms ±5%, 1/4 w.		19A701743P1	Pad. (Located behind S601 & S602 knobs).
C612	19A702250P112	Polyester: .068 uF ±10%, 50 VDCW; sim to NISSEI TYPE AMZ.	R621B	19A700019P25	Deposited carbon: 100 ohms ±5%, 1/4 w.	1	19C328587P1	Pushbutton. (Used with S602).
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(19D900974, Sh. 4, Rev. 7)

SCHEMATIC DIAGRAM

136-174 MHz, 40 WATT WIDEBAND RECEIVER BOARD

LBI31243

SYMBOL	GE PART NO.	DESCRIPTION
	NP280878P17	Nameplate. (MONITOR).
	NP280878P15	Nameplate. (MODE A-B).
	19A700032P1	Lockwasher, internal tooth: No. 2. (Secures R617).
	19A701312P2	Flatwasher, metric: steel. (Secures R617).
	19C851075P1	Knob. (R617).
	19A703313P2	Screw. (Secures R617 knob).
	19A701516P2	Insulator, plate. (Quantity 2 - Used with Z501)
	19A116022P1	Insulator, plate. (Used with Q204).
	19A701093P4	Strap. (Located on Q202 mounting screw).
	19A701706P1	Heat sink. (Q202).
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PRODUCTION CHANGES

Changes in the equipment to improve performance or to simplify circuits are identified by a "Revision Letter," which is stamped after the model number of the unit. The revision stamped on the unit includes all previous revisions. Refer to the Parts List for descriptions of parts affected by these revisions.

REV A. - 136-174 MHz Wideband-Transmit/Receive Board 19D900970G1,3

To improve operation of the Power Control Circuit, to incorporate squelch switch circuit, to assure compatability with dual priority scan, to improve operation of audio amplifier, and to facilitate manufacturing. The following components were changed: C120, C231B, C232B, C234, C235, C606-C608, C610, C621, D101, L210A, R119, R125, R126, R512, R608, R609, R611, R612, R633, R635, Q105, Q106 and Q601-Q603. The following components were added: C510, C524, D203, L214B, L217B, Q605, Q606, R206 and R632-R637. R127 was deleted.

Part numbers for the changed components were:

C120 was: 19A701624P14 - Ceramic disc: 18 pF ±5%, 500 VDCW, temp coef 0 PPM ±30. (Used in G1).

C231B was: 19A701624P19 - Ceramic, disc: 30 pF ±5%, 500 VDCW, temp coef 0 PPM ±30. (Used in G1).

C232B was: 19A701624P11 - Ceramic, disc: 13 pF ±5%, 500 VDCW, temp coef 0 PPM ±30. (Used in G3).

C606 was: 19A700234P8 - Polyester: 0.15 uF ±10%, 50 VDCW; sim to NISSEI AMXV or AMZV.

C607 was: 19A701534P4 - Tantalum: 1 uF +20%, 35 VDCW.

C610 was: 19A701534P3 - Tantalum: 0.47 uF ±20%, 35 VDCW.

C621 was: 19A701534P13 - Tantalum: .68 uF +20%, 35 VDCW.

D101 was: 19A700025P11 - Silicon, Zener: 400 mW max; sim to BZX55-C12.

L210A was: 19A701421P3 - Coil. (Used in G1).

Q105/Q106/Q601/Q602 was: 19A700023P1 - Silicon, NPN; sim to Type 2N3904.

Q603 was: 19A700022P1 - Silicon, PNP; sim to Type 2N3906.

R119 was: 19A700019P37 - Deposited carbon: 1K ohms ±5%, 1/4 w.

R125 was: 19A700019P49 - Deposited carbon: 10K ohms \pm 5%, 1/4 w.

R126 was: 19A700019P37 - Deposited carbon: 1K ohmw ±5%, 1/4 w.

R127 was: 19A700019P51 - Deposited carbon: 15K ohms $\pm 5\%$, 1/4 w.

1/4 W.

R512 was: 19A700019P25 - Deposited carbon: 100 ohms ±5%, 1/4 w.

R608 was: 19A700019P47 - Deposited carbon: 6.8K ohms ±5%,

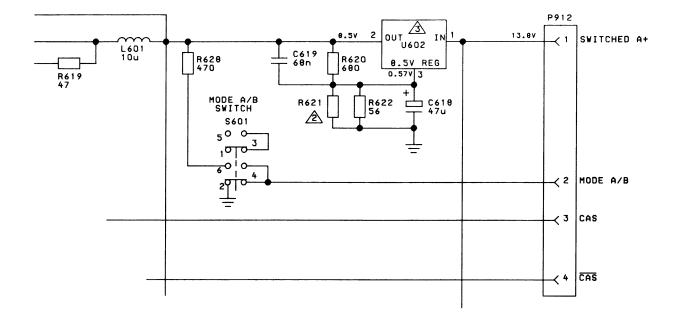
R609 was: 19A700019P60 - Deposited carbon: 82K ohms \pm 5%, 1/4 w.

R611 was: 19A700019P44 - Deposited carbon: 3.9K ohms ±5%,

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R612 was: 19A700019P29 - Deposited carbon: 220 ohms ±5%, 1/4 w.

Old Schematic Diagram was:



This addendum describes Revision Letter changes that are not yet included in the publication.

REV.B- 136-174 MHZ 40 WATT TRANSMIT/RECEIVE BOARD 19D900970G1

To increase RF Power output. Changed C216. The new part number for C216 is: C216- 19A701624P22; Ceramic disc: $39pF \pm 5\%$, 500vdcw., temp coef 0 ppm +30.

ADDENDUM NO.2 TO LBI31243B

This addendum describes Revision Letter changes that are not yet included in the publication.

REV.B- 136-174 MHZ 40 WATT TRANSMIT/RECEIVE BOARD 19D900470G3
REV.C- 136-174 MHZ 40 WATT TRANSMIT/RECEIVE BOARD 19D900470G1

To improve transmitter operation when operating under reduced power. Changed C129A to 18pF in group 1 boards and C235 to 0.1uF in group 3 boards. New part numbers are: C129A- 19A701624P14- Ceramic disc: 12 pF $\pm 5\%$, 500vdcw, temp coef. 0 ppm ± 30 (used in group 1). C235- 19A7022509113- Polyester: 0.1uF $\pm 10\%$, 50 vdcw.